

INTERNATIONAL STANDARD

NORME INTERNATIONALE



**Field device integration (FDI) –
Part 6: Technology Mapping**

**Intégration des appareils de terrain (FDI) –
Partie 6: Mapping de technologies**



THIS PUBLICATION IS COPYRIGHT PROTECTED

Copyright © 2021 IEC, Geneva, Switzerland

All rights reserved. Unless otherwise specified, no part of this publication may be reproduced or utilized in any form or by any means, electronic or mechanical, including photocopying and microfilm, without permission in writing from either IEC or IEC's member National Committee in the country of the requester. If you have any questions about IEC copyright or have an enquiry about obtaining additional rights to this publication, please contact the address below or your local IEC member National Committee for further information.

Droits de reproduction réservés. Sauf indication contraire, aucune partie de cette publication ne peut être reproduite ni utilisée sous quelque forme que ce soit et par aucun procédé, électronique ou mécanique, y compris la photocopie et les microfilms, sans l'accord écrit de l'IEC ou du Comité national de l'IEC du pays du demandeur. Si vous avez des questions sur le copyright de l'IEC ou si vous désirez obtenir des droits supplémentaires sur cette publication, utilisez les coordonnées ci-après ou contactez le Comité national de l'IEC de votre pays de résidence.

IEC Central Office
3, rue de Varembe
CH-1211 Geneva 20
Switzerland

Tel.: +41 22 919 02 11
info@iec.ch
www.iec.ch

About the IEC

The International Electrotechnical Commission (IEC) is the leading global organization that prepares and publishes International Standards for all electrical, electronic and related technologies.

About IEC publications

The technical content of IEC publications is kept under constant review by the IEC. Please make sure that you have the latest edition, a corrigendum or an amendment might have been published.

IEC publications search - webstore.iec.ch/advsearchform

The advanced search enables to find IEC publications by a variety of criteria (reference number, text, technical committee, ...). It also gives information on projects, replaced and withdrawn publications.

IEC Just Published - webstore.iec.ch/justpublished

Stay up to date on all new IEC publications. Just Published details all new publications released. Available online and once a month by email.

IEC Customer Service Centre - webstore.iec.ch/csc

If you wish to give us your feedback on this publication or need further assistance, please contact the Customer Service Centre: sales@iec.ch.

IEC online collection - oc.iec.ch

Discover our powerful search engine and read freely all the publications previews. With a subscription you will always have access to up to date content tailored to your needs.

Electropedia - www.electropedia.org

The world's leading online dictionary on electrotechnology, containing more than 22 000 terminological entries in English and French, with equivalent terms in 18 additional languages. Also known as the International Electrotechnical Vocabulary (IEV) online.

A propos de l'IEC

La Commission Electrotechnique Internationale (IEC) est la première organisation mondiale qui élabore et publie des Normes internationales pour tout ce qui a trait à l'électricité, à l'électronique et aux technologies apparentées.

A propos des publications IEC

Le contenu technique des publications IEC est constamment revu. Veuillez vous assurer que vous possédez l'édition la plus récente, un corrigendum ou amendement peut avoir été publié.

Recherche de publications IEC -

webstore.iec.ch/advsearchform

La recherche avancée permet de trouver des publications IEC en utilisant différents critères (numéro de référence, texte, comité d'études, ...). Elle donne aussi des informations sur les projets et les publications remplacées ou retirées.

IEC Just Published - webstore.iec.ch/justpublished

Restez informé sur les nouvelles publications IEC. Just Published détaille les nouvelles publications parues. Disponible en ligne et une fois par mois par email.

Service Clients - webstore.iec.ch/csc

Si vous désirez nous donner des commentaires sur cette publication ou si vous avez des questions contactez-nous: sales@iec.ch.

IEC online collection - oc.iec.ch

Découvrez notre puissant moteur de recherche et consultez gratuitement tous les aperçus des publications. Avec un abonnement, vous aurez toujours accès à un contenu à jour adapté à vos besoins.

Electropedia - www.electropedia.org

Le premier dictionnaire d'électrotechnologie en ligne au monde, avec plus de 22 000 articles terminologiques en anglais et en français, ainsi que les termes équivalents dans 16 langues additionnelles. Egalement appelé Vocabulaire Electrotechnique International (IEV) en ligne.

INTERNATIONAL STANDARD

NORME INTERNATIONALE



**Field device integration (FDI) –
Part 6: Technology Mapping**

**Intégration des appareils de terrain (FDI) –
Partie 6: Mapping de technologies**

INTERNATIONAL
ELECTROTECHNICAL
COMMISSION

COMMISSION
ELECTROTECHNIQUE
INTERNATIONALE

ICS 25.040.40; 35.100.05

ISBN 978-2-8322-9312-6

**Warning! Make sure that you obtained this publication from an authorized distributor.
Attention! Veuillez vous assurer que vous avez obtenu cette publication via un distributeur agréé.**

CONTENTS

FOREWORD.....	4
INTRODUCTION.....	6
1 Scope.....	7
2 Normative references	7
3 Terms, definitions, abbreviated terms, symbols and conventions	7
3.1 Terms and definitions.....	7
3.2 Abbreviated terms.....	8
3.3 Symbols.....	8
3.4 Conventions.....	8
4 Technical concepts.....	8
4.1 General.....	8
4.1.1 Overview	8
4.1.2 Platforms	9
4.1.3 FDI Type Library.....	9
4.2 UIP representation.....	10
4.3 UIP executable representation	11
4.4 UIP executable compatibility rules	11
4.5 Allowed .NET Common Language Run-time versions.....	11
4.5.1 General	11
4.5.2 CLR compatibility strategy	11
4.5.3 How to identify the .NET target platform of a UIP	12
4.6 UIP Deployment.....	12
4.7 UIP Lifecycle.....	13
4.7.1 General	13
4.7.2 UIP Assembly activation steps.....	13
4.7.3 UIP Assembly deactivation steps	15
4.8 Interaction between an FDI Client and a UIP.....	16
4.8.1 Handling of standard UI elements	16
4.8.2 Non-blocking service execution	16
4.8.3 Blocking service execution.....	17
4.8.4 Cancel service execution	18
4.8.5 Threading	19
4.8.6 Timeout	19
4.8.7 Exception handling	20
4.8.8 Type safe interfaces	21
4.8.9 Globalization and localization	21
4.8.10 WPF Control handling.....	21
4.8.11 Win Form handling.....	21
4.9 Security	21
4.9.1 General	21
4.9.2 Access permissions	22
4.9.3 Code identity concept	22
5 Interface definition.....	23
Figure 1 – FDI Type Library structure.....	10

Figure 2 – .NET surrogate process	12
Figure 3 – Identification of Run-time Version.....	12
Figure 4 – IAsyncPattern based asynchronous service execution example.....	17
Figure 5 – Blocking service execution example using IAsyncResult based pattern	18
Figure 6 – Cancel service processing sequence example	18
Figure 7 – Exception source	20
Table 1 – Technology edition reference	9
Table 2 – Base Property Services	23
Table 3 – Device Model Services	23
Table 4 – Access Control Services.....	24
Table 5 – Direct Access Services.....	24
Table 6 – Hosting Services	24
Table 7 – UIP Services	26
Table 8 – Base Data Types.....	26
Table 9 – Special Types	27

INTERNATIONAL ELECTROTECHNICAL COMMISSION

FIELD DEVICE INTEGRATION (FDI) –**Part 6: Technology Mapping****FOREWORD**

- 1) The International Electrotechnical Commission (IEC) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, IEC publishes International Standards, Technical Specifications, Technical Reports, Publicly Available Specifications (PAS) and Guides (hereafter referred to as "IEC Publication(s)"). Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
- 2) The formal decisions or agreements of IEC on technical matters express, as nearly as possible, an international consensus of opinion on the relevant subjects since each technical committee has representation from all interested IEC National Committees.
- 3) IEC Publications have the form of recommendations for international use and are accepted by IEC National Committees in that sense. While all reasonable efforts are made to ensure that the technical content of IEC Publications is accurate, IEC cannot be held responsible for the way in which they are used or for any misinterpretation by any end user.
- 4) In order to promote international uniformity, IEC National Committees undertake to apply IEC Publications transparently to the maximum extent possible in their national and regional publications. Any divergence between any IEC Publication and the corresponding national or regional publication shall be clearly indicated in the latter.
- 5) IEC itself does not provide any attestation of conformity. Independent certification bodies provide conformity assessment services and, in some areas, access to IEC marks of conformity. IEC is not responsible for any services carried out by independent certification bodies.
- 6) All users should ensure that they have the latest edition of this publication.
- 7) No liability shall attach to IEC or its directors, employees, servants or agents including individual experts and members of its technical committees and IEC National Committees for any personal injury, property damage or other damage of any nature whatsoever, whether direct or indirect, or for costs (including legal fees) and expenses arising out of the publication, use of, or reliance upon, this IEC Publication or any other IEC Publications.
- 8) Attention is drawn to the Normative references cited in this publication. Use of the referenced publications is indispensable for the correct application of this publication.
- 9) Attention is drawn to the possibility that some of the elements of this IEC Publication may be the subject of patent rights. IEC shall not be held responsible for identifying any or all such patent rights.

International Standard IEC 62769-6 has been prepared by subcommittee 65E: Devices and integration in enterprise systems, of IEC technical committee 65: Industrial-process measurement, control and automation.

This second edition cancels and replaces the first edition published in 2015. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) redesign of the security concept for UIP execution.

The text of this International Standard is based on the following documents:

FDIS	Report on voting
65E/763/FDIS	65E/773/RVD

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 62769 series, published under the general title *Field Device Integration (FDI)*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

IMPORTANT – The 'colour inside' logo on the cover page of this publication indicates that it contains colours which are considered to be useful for the correct understanding of its contents. Users should therefore print this document using a colour printer.

INTRODUCTION

The IEC 62769 series has the general title *Field Device Integration (FDI)* and the following parts:

- Part 1: Overview
- Part 2: FDI Client
- Part 3: FDI Server
- Part 4: FDI Packages
- Part 5: FDI Information Model
- Part 6: FDI Technology Mapping
- Part 7: FDI Communication Devices
- Part 100: Profiles – Generic Protocol Extensions
- Part 101-1: Profiles – Foundation Fieldbus H1
- Part 101-2: Profiles – Foundation Fieldbus HSE
- Part 103-1: Profiles – PROFIBUS
- Part 103-4: Profiles – PROFINET
- Part 109-1: Profiles – HART and WirelessHART
- Part 115-2: Profiles – Protocol-specific Definitions for Modbus RTU
- Part 150-1: Profiles – ISA 100.11a

FIELD DEVICE INTEGRATION (FDI) –

Part 6: Technology Mapping

1 Scope

This part of IEC 62769 specifies the technology mapping for the concepts described in the Field Device Integration (FDI) standard. The technology mapping focuses on implementation regarding the components FDI Client and User Interface Plug-in (UIP) that are specific only to the WORKSTATION platform/.NET as defined in IEC 62769-4.

2 Normative references

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 61804 (all parts), *Function blocks (FB) for process control and Electronic Device Description Language (EDDL)*

IEC 62769-1, *Field Device Integration (FDI) – Part 1: Overview*

IEC 62769-2, *Field Device Integration (FDI) – Part 2: FDI Client*

IEC 62769-4, *Field Device Integration (FDI) – Part 4: FDI Packages*

IEC 62541 (all parts), *OPC Unified Architecture*

ISO/IEC 19505-1, *Information technology – Object Management Group Unified Modeling Language (OMG UML) – Part 1: Infrastructure*

ISO/IEC 29500, (all parts) *Information technology – Document description and processing languages – Office Open XML File Formats*

3 Terms, definitions, abbreviated terms, symbols and conventions

3.1 Terms and definitions

For the purposes of this document, the terms and definitions given in IEC 62769-1 as well as the following apply.

ISO and IEC maintain terminological databases for use in standardization at the following addresses:

- IEC Electropedia: available at <http://www.electropedia.org/>
- ISO Online browsing platform: available at <http://www.iso.org/obp>

3.1.1

Application Domain

isolated environment where applications execute